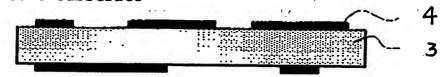
Docket No.: 358362011300

App No.: Not Yet Assigned Inventor: Masayuki TSUTSUMI et al.

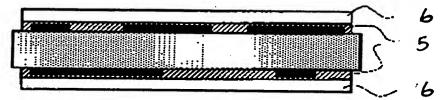
Title: POLYIMIDE FILM REPLACEMENT SHEET

FIG. 3

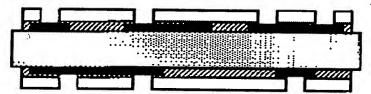
(a) core substrate



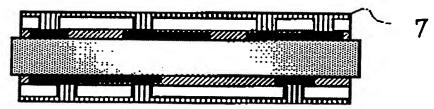
(b) first interlayer insulation layer formation



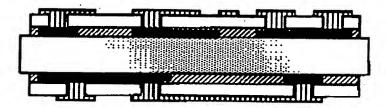
(c) via-hole perforation



(d) via fill plating



(e) first buildup layer pattern formation



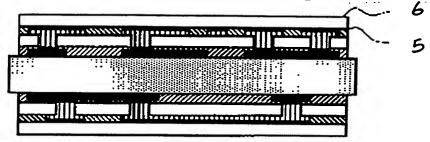
App No.: Not Yet Assigned

Inventor: Masayuki TSUTSUMI et al. Title: POLYIMIDE FILM REPLACEMENT SHEET

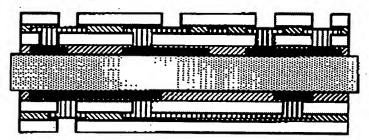
Docket No.: 358362011300

FIG. 4

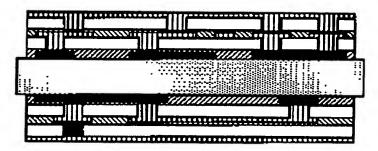
(e) second interlayer insulation layer formation



(b) via-hole perforation



(c) via fill plating



(d) second buildup layer pattern formation

